



Description

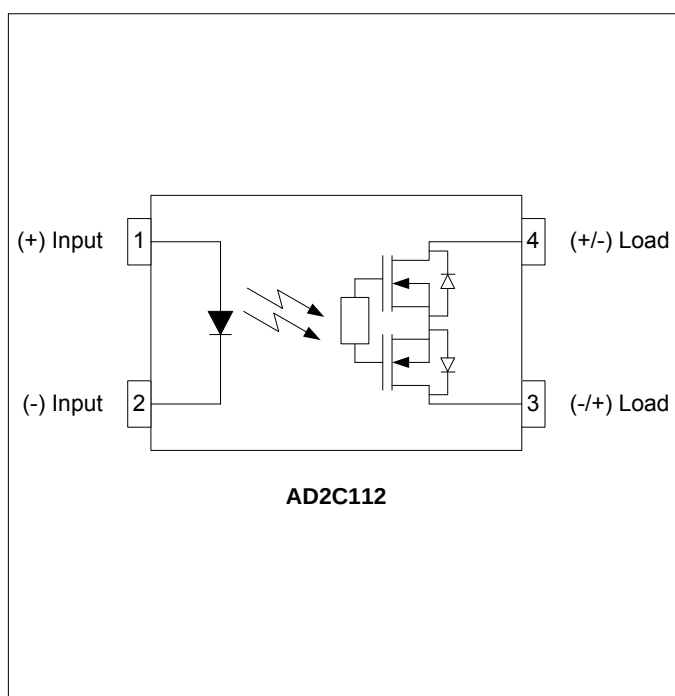
The AD2C112 is a bi-directional, single-pole, single-throw, normally closed multipurpose relay. It is designed to replace electro-mechanical relays in general purpose switching applications. The relay consists of an integrated circuit that drives two rugged drain-to-drain depletion type DMOS transistors - optically coupled to a light emitting diode. The device comes with up to 5kV input to output isolation.

The AD2C112 comes standard in a miniature 4 pin DIP package making it ideal for high-density board applications.

Applications

- Reed Relay Replacement
- Meter Reading Systems
- Data Acquisition
- Medical Equipment
- Battery Monitoring
- Safety Systems

Schematic Diagram



Features

- Compact 4 pin DIP/SMD Package
- High Isolation Voltage (up to 5kV_{RMS})
- Low Input Control Current (2.5mA TYP)
- 25Ω Typical On Resistance
- 120mA Maximum Continuous Load Current
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL: File # E201932
VDE: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature-55 to +125°C
Operating Temperature-40 to +85°C
Continuous Input Current.....50mA
Transient Input Current.....500mA
Reverse Input Control Voltage5V
Input Power Dissipation.....40mW
Output Power Dissipation500mW
Solder Temperature – Wave (10sec).....260°C
Solder Temperature – IR Reflow (10sec).....260°C

Ordering Information

Part Number	Description
AD2C112	4 pin DIP, (100/Tube)
AD2C112-H	5kV _{RMS} Viso, 8 pin DIP, (100/Tube)
AD2C112-S	4 pin SMD, (100/Tube)
AD2C112-HS	5kV _{RMS} , 4 pin SMD, (100/Tube)
AD2C112-STR	4 pin SMD, Tape & Reel (2000/Reel)
AD2C112-HSTR	5kV _{RMS} , 4 pin SMD, Tape & Reel (2000/Reel)

NOTE: Suffixes listed above are not included in marking on device for part number identification

Electrical Characteristics, $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.2	1.5	V	$I_F=10\text{mA}$
LED Reverse Voltage	BV_R	5	-	-	V	$I_R=10\mu\text{A}$
Turn-On Current	I_F	-	0.5	-	mA	$I_O=120\text{mA}$
Turn-Off Current	I_{FOFF}	-	2.5	5	mA	$I_O=120\text{mA}$
Output Specifications						
Blocking Voltage	V_B	400	-	-	V	$I_F=5\text{mA}, I_O=1\mu\text{A}$
Continuous Load Current	I_O	-	-	120	mA	$I_F=0\text{mA}$
On Resistance	R_{ON}	-	25	35	Ω	$I_F=0\text{mA}, I_O=120\text{mA}$
Leakage Current	I_{leak}	-	0.2	1	μA	$I_F=5\text{mA}, V_O=400\text{V}$
Output Capacitance	C_{OUT}	-	20	-	pF	$I_F=5\text{mA}, f=1.0\text{MHz}$
Offset Voltage	V_{OFFSET}	-	-	0.2	mV	$I_F=0\text{mA}$
Coupled Specifications						
Turn-On Time	T_{ON}	-	0.3	1	mS	$I_F=0\text{mA}, I_O=120\text{mA}$
Turn-Off Time	T_{OFF}	-	1	5	mS	$I_F=5\text{mA}, I_O=120\text{mA}$
Coupled Capacitance	C_{COUPLED}	-	3	-	pF	
Contact Transient Ratio	-	2,000	7,000	0	V/ μS	dV = 50V
Isolation Specifications						
Isolation Voltage (-H Option)	V_{ISO}	3,750	-	-	V_{RMS}	$\text{RH} \leq 50\%, t=1\text{min}$
		5,000	-	-		
Input-Output Resistance	$R_{\text{I-O}}$	-	10^{12}	-	Ω	$V_{\text{I-O}} = 500V_{\text{DC}}$

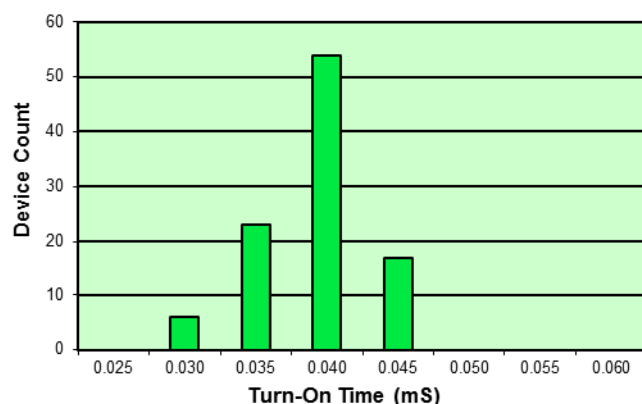
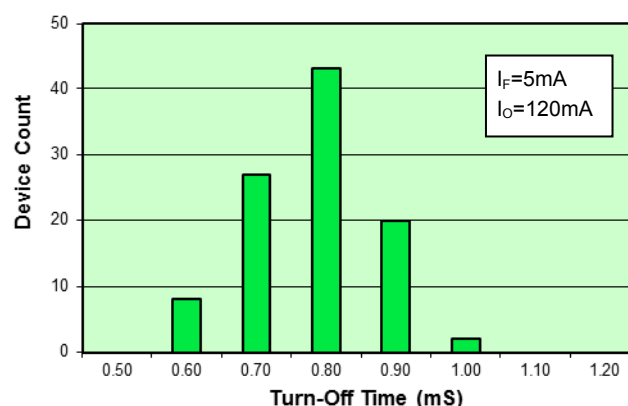
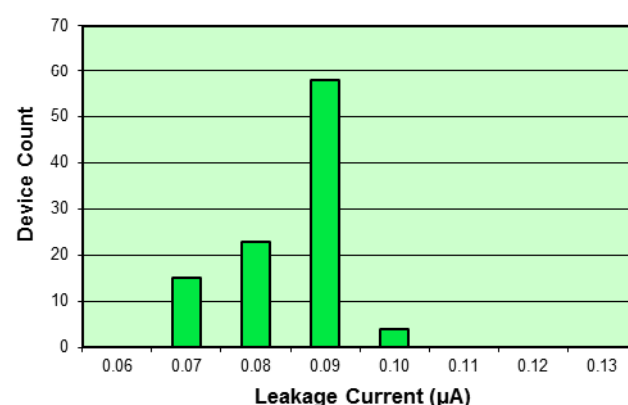
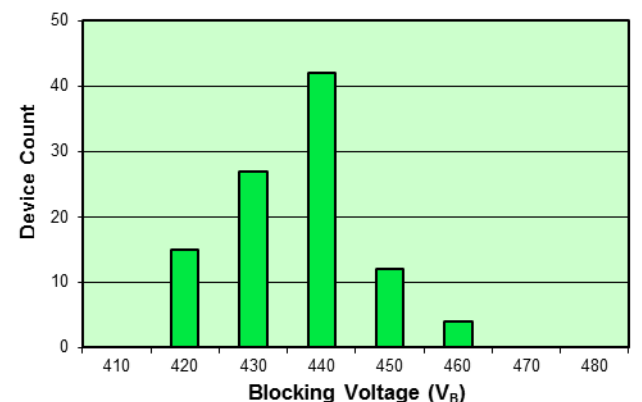
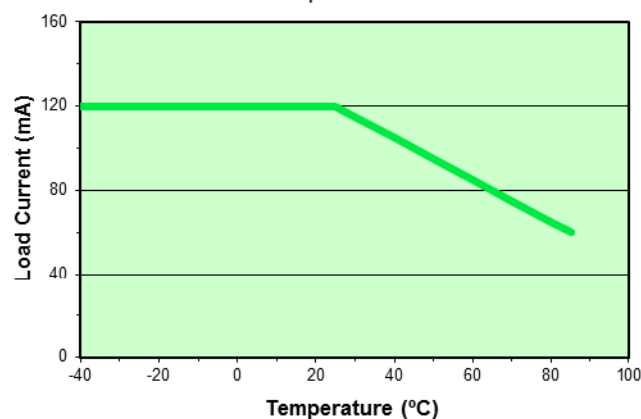
AD2C112 Performance & Characteristics Plots, $T_A = 25^\circ\text{C}$ (unless otherwise specified)
Figure 1: Typical Turn-On Time Distribution
(N = 100, $T_a = 25^\circ\text{C}$)

Figure 2: Typical Turn-Off Time Distribution
(N = 100, $T_a = 25^\circ\text{C}$)

Figure 3: Typical On-Resistance Distribution
(N = 100, $T_a = 25^\circ\text{C}$)

Figure 4: Typical Output Leakage Current Distribution
(N = 100, $T_a = 25^\circ\text{C}$)

Figure 5: Typical Blocking Voltage Distribution
(N = 100, $T_a = 25^\circ\text{C}$)

Figure 6: Maximum Load Current vs. Temperature


AD2C112 Solder Temperature Profile Recommendations

(1) Infrared Reflow:

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:

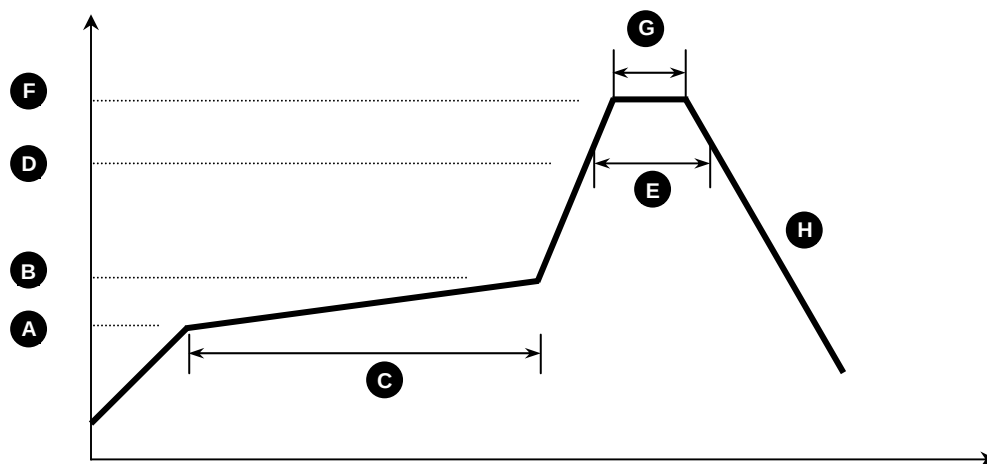


Figure 1

Process Step	Description	Parameter
A	Preheat Start Temperature (°C)	150°C
B	Preheat Finish Temperature (°C)	180°C
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (°C)	230°C
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (°C)	260°C
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (°C/s)	<6°C/s

(2) Wave Solder:

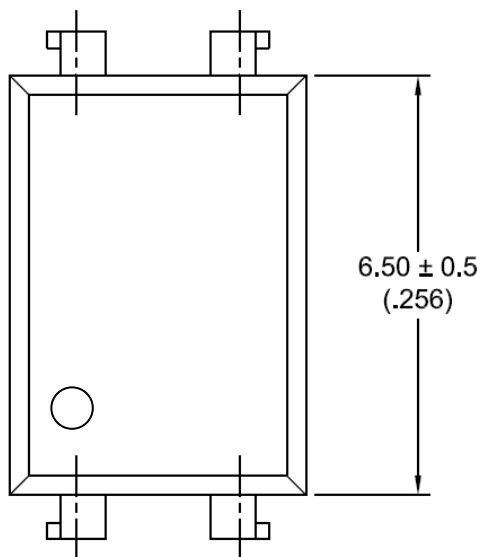
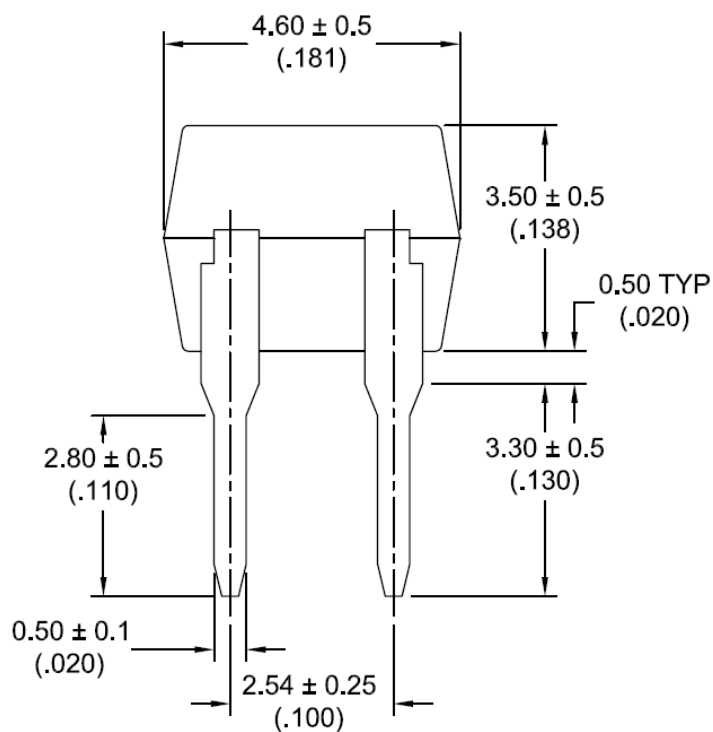
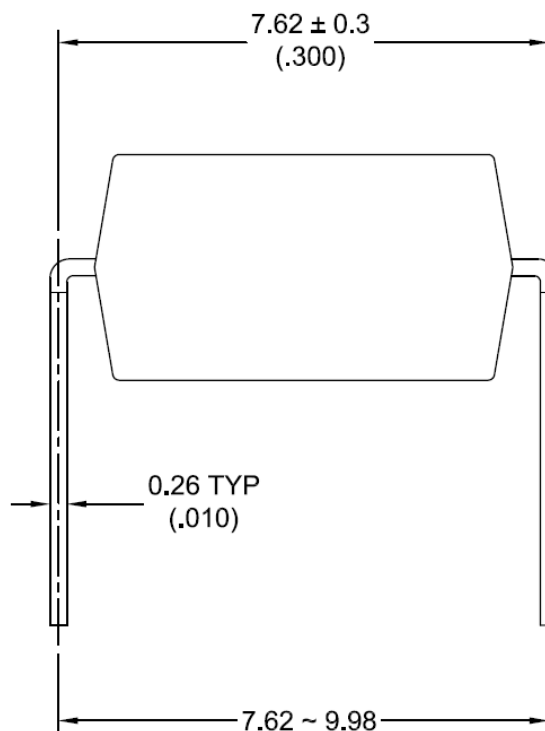
Maximum Temperature: 260°C (at terminal)
Maximum Time: 10s
Pre-heating: 100 - 150°C (30 - 90s)
Single Occurrence

(3) Hand Solder:

Maximum Temperature: 350°C (at tip of soldering iron)
Maximum Time: 3s
Single Occurrence

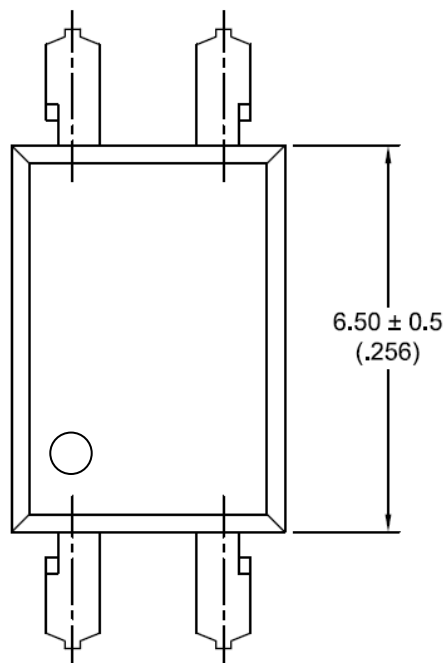
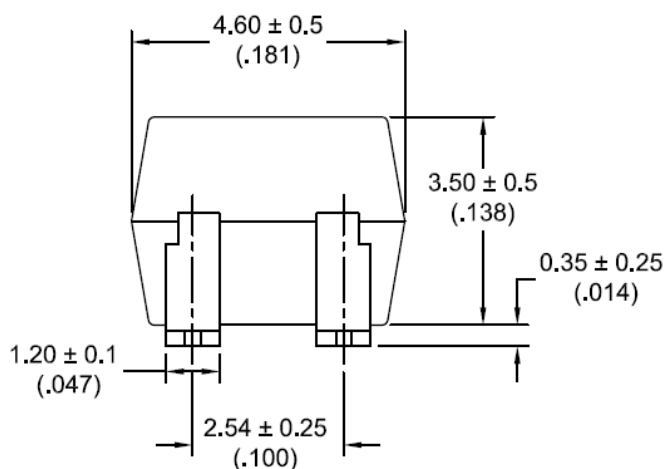
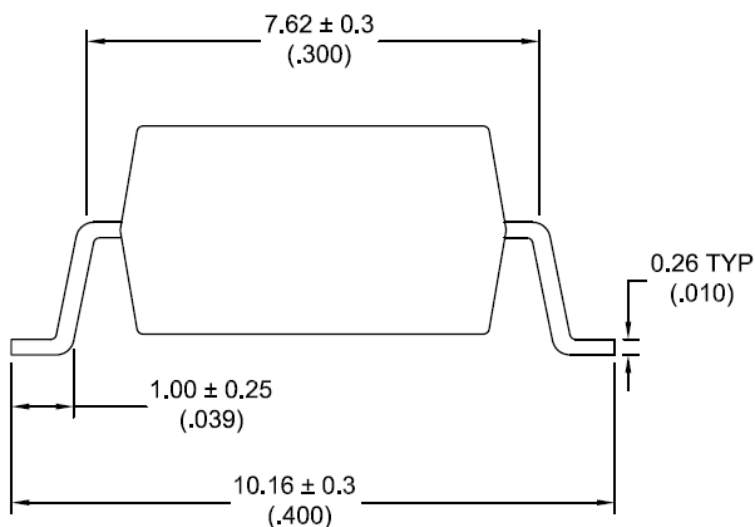
AD2C112 Package Dimensions

4 PIN DIP Package

Note: All dimensions in millimeters with inches ["] in parenthesis ()


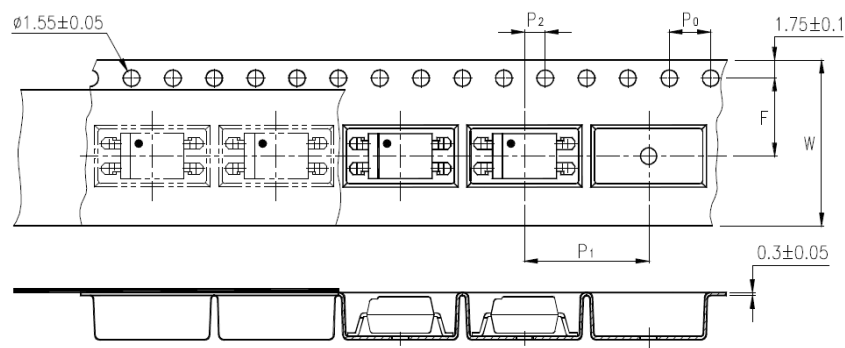
AD2C112 Package Dimensions

4 PIN SMD Surface Mount Package (-S)

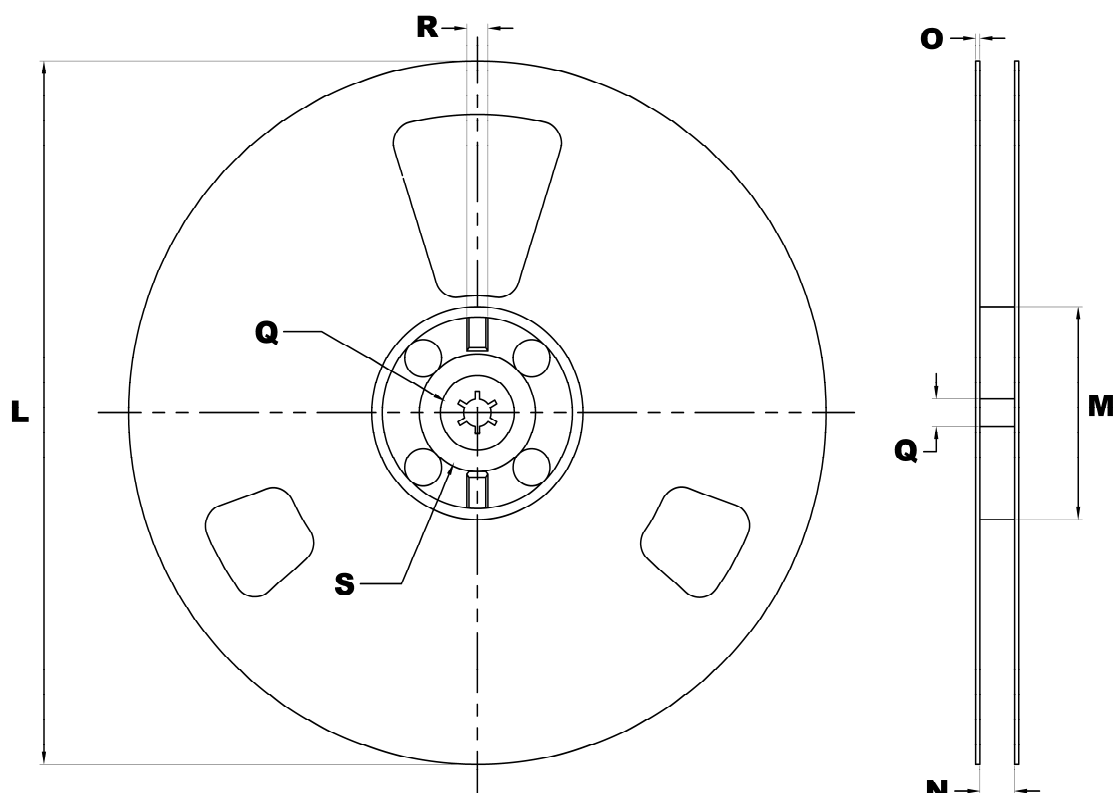
Note: All dimensions in millimeters with inches ["] in parenthesis ()


AD2C112 Package Dimensions

4 PIN SMD Tape & Reel (-STR)

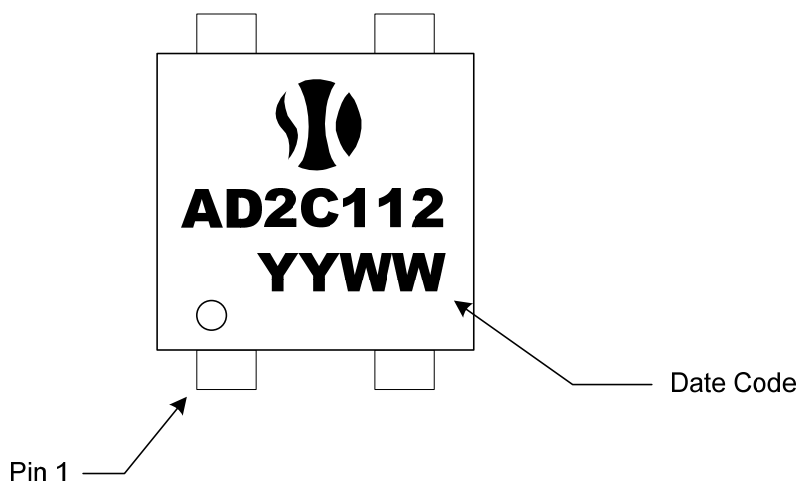
Note: All dimensions in millimeters


F	P0	P1	P2	W
7.5±0.1	4.0±0.1	12.0±0.1	2.0±0.1	16.0±0.3



L	M	N	O	Q	R	S
330±2	101.6±1	16.4±0.2	2.0±0.2	R13±0.5	1.50±0.5	R10±1

AD2C112 Package Marking



AD2C112 Package Weights

Device	Single Unit	Full Tube (100pcs)	Full Pouch (10 tubes)	Full Reel (2000pcs)
AD2C112-(H)	0.23	39	400	-
AD2C112-(H)S	0.22	38	390	-
AD2C112-(H)STR	0.22	-	-	920

Note: All weights above are in GRAMS, and include packaging materials where applicable

DISCLAIMER

Solid State Optronics (SSO) makes no warranties or representations with regards to the completeness and accuracy of this document. SSO reserves the right to make changes to product description, specifications at any time without further notices.

SSO shall not assume any liability arising out of the application or use of any product or circuit described herein. Neither circuit patent licenses nor indemnity are expressed or implied.

Except as specified in SSO's Standard Terms & Conditions, SSO disclaims liability for consequential or other damage, and we make no other warranty, expressed or implied, including merchantability and fitness for particular use.

LIFE SUPPORT POLICY

SSO does not authorize use of its devices in life support applications wherein failure or malfunction of a device may lead to personal injury or death. Users of SSO devices in life support applications assume all risks of such use and agree to indemnify SSO against any and all damages resulting from such use. Life support devices are defined as devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when used properly in accordance with instructions for use can be reasonably expected to result in significant injury to the user, or (d) a critical component of a life support device or system whose failure can be reasonably expected to cause failure of the life support device or system, or to affect its safety or effectiveness.